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(54) HEAT SINK STRUCTURE

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(57)ABSTRACT

A heat sink structure includes: a corrugated fin that is made of metal, and has a cross section in a wave form and a plate surface in which a plurality of through holes are opened; heat absorbing portions and that absorb heat from a cooling target object and transmit the heat to the corrugated fin; and a fluid flow path that allows cooling fluid to be supplied toward the plate surface of the corrugated fin and allows the cooling fluid to flow along the through holes. The heat transmitted from the heat absorbing portions and to the corrugated fin is radiated in the cooling fluid passing through the through holes.

